

## Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- Green Device Available

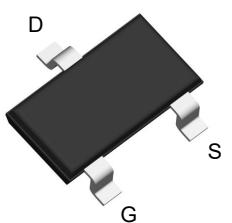
## Product Summary



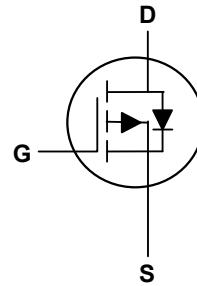
$V_{DS}$	-40	V
$I_D$	-3.2	A
$R_{DS(ON)}$ (at $V_{GS}=-4.5V$ )	70	mΩ
$R_{DS(ON)}$ (at $V_{GS}=-2.5V$ )	100	mΩ

## Applications

- High Frequency Point-of-Load, Synchronous Buck Converter for MB/NB/UMPC/VGA
- Networking DC-DC Power System
- Load Switch



SOT23-3L Top View



## Absolute Maximum Ratings( $T_c=25^\circ C$ , unless otherwise noted)

Parameter	Symbol	Rating		Units
		10S	Steady State	
Drain-Source Voltage	$V_{DS}$	-40		V
Gate-Source Voltage	$V_{GS}$	$\pm 20$		V
Continuous Drain Current, $V_{GS} @ -4.5V^1$	$I_D @ T_A=25^\circ C$	-3.7	-3.2	A
Continuous Drain Current, $V_{GS} @ -4.5V^1$	$I_D @ T_A=70^\circ C$	-3.0	-2.6	A
Pulsed Drain Current <sup>2</sup>	$I_{DM}$	-16.1		A
Total Power Dissipation <sup>3</sup>	$P_D @ T_A=25^\circ C$	1.32	1	W
Total Power Dissipation <sup>3</sup>	$P_D @ T_A=70^\circ C$	0.84	0.64	W
Storage Temperature Range	$T_{STG}$	-55 to 150		°C
Operating Junction Temperature Range	$T_J$	-55 to 150		°C

## Thermal Characteristics

Parameter	Symbol	Typ	Max	Unit
Thermal Resistance Junction-Ambient <sup>1</sup> ( $t \leq 10s$ )	$R_{\theta JA}$	---	95	°C/W
Thermal Resistance Junction-Ambient <sup>1</sup>		---	125	°C/W
Thermal Resistance Junction-Case <sup>1</sup>	$R_{\theta JC}$	---	80	°C/W

**Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$V_{\text{GS}}=0\text{V}$ , $I_D=-250\mu\text{A}$	-40	---	---	V
$\text{BV}_{\text{DSS}}$ Temperature Coefficient	$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	Reference to $25^\circ\text{C}$ , $I_D=-1\text{mA}$	---	-0.018	---	$\text{V}/^\circ\text{C}$
Static Drain-Source On-Resistance <sup>2</sup>	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}}=-4.5\text{V}$ , $I_D=-3\text{A}$	---	---	70	$\text{m}\Omega$
		$V_{\text{GS}}=-2.5\text{V}$ , $I_D=-2\text{A}$	---	---	100	$\text{m}\Omega$
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{GS}}=V_{\text{DS}}$ , $I_D = -250\mu\text{A}$	-1.0	---	-2.5	V
$V_{\text{GS}(\text{th})}$ Temperature Coefficient	$\Delta V_{\text{GS}(\text{th})}$		---	2.5	---	$\text{mV}/^\circ\text{C}$
Drain-Source Leakage Current	$I_{\text{DSS}}$	$V_{\text{DS}}=-24\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	-1	$\mu\text{A}$
		$V_{\text{DS}}=-24\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=55^\circ\text{C}$	---	---	-5	$\mu\text{A}$
Gate-Source Leakage Current	$I_{\text{GSS}}$	$V_{\text{GS}}=\pm 20\text{V}$ , $V_{\text{DS}}=0\text{V}$	---	---	$\pm 100$	nA
Forward Transconductance	$g_{\text{fs}}$	$V_{\text{DS}}=-5\text{V}$ , $I_D=-3\text{A}$	---	5.8	---	S
Total Gate Charge (-4.5V)	$Q_g$	$V_{\text{DS}}=-32\text{V}$ , $V_{\text{GS}}=-4.5\text{V}$ , $I_D=-3\text{A}$	---	6.4	---	nC
Gate-Source Charge	$Q_{\text{gs}}$		---	2.1	---	
Gate-Drain Charge	$Q_{\text{gd}}$		---	2.5	---	
Turn-On Delay Time	$T_{\text{d}(\text{on})}$	$V_{\text{DD}}=-20\text{V}$ , $V_{\text{GS}}=-4.5\text{V}$ , $R_G=3.3\Omega$ , $I_D=-3\text{A}$	---	4.2	---	ns
Rise Time	$T_r$		---	23	---	
Turn-Off Delay Time	$T_{\text{d}(\text{off})}$		---	26.8	---	
Fall Time	$T_f$		---	20.6	---	
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}}=-15\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	620	---	pF
Output Capacitance	$C_{\text{oss}}$		---	65	---	
Reverse Transfer Capacitance	$C_{\text{rss}}$		---	53	---	

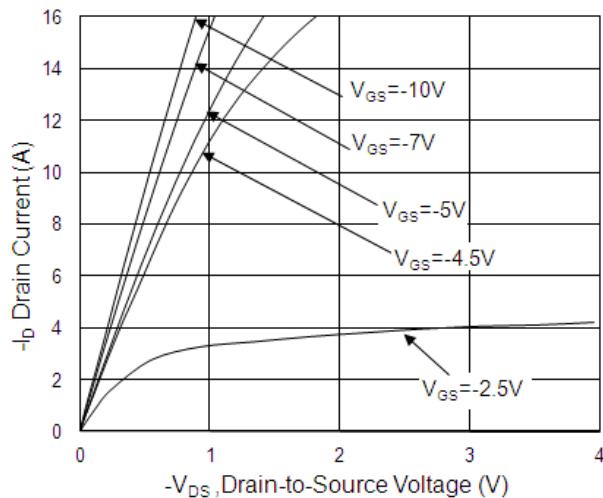
**Drain-Source Diode Characteristics**

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Continuous Source Current <sup>1,4</sup>	$I_s$	$V_G=V_D=0\text{V}$ , Force Current	---	---	-3.2	A
Pulsed Source Current <sup>2,4</sup>	$I_{\text{SM}}$		---	---	-16.1	A
Diode Forward Voltage <sup>2</sup>	$V_{\text{SD}}$	$V_{\text{GS}}=0\text{V}$ , $I_s=-1\text{A}$ , $T_J=25^\circ\text{C}$	---	---	-1	V

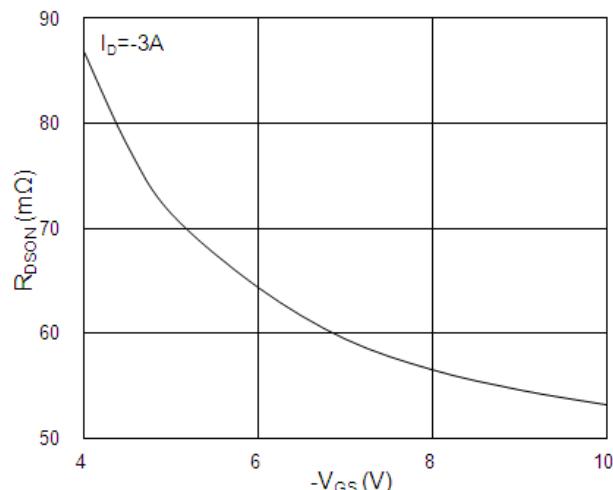
**Note:**

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$
- 3.The power dissipation is limited by  $150^\circ\text{C}$  junction temperature
- 4.The data is theoretically the same as  $I_D$  and  $I_{\text{DM}}$  , in real applications , should be limited by total power dissipation.

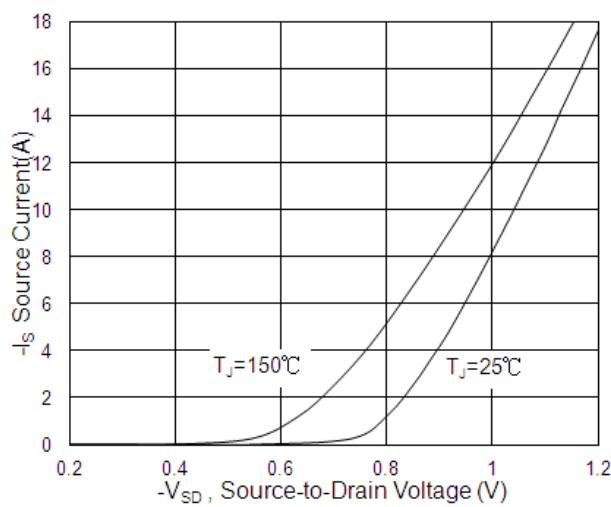
## Typical Characteristics



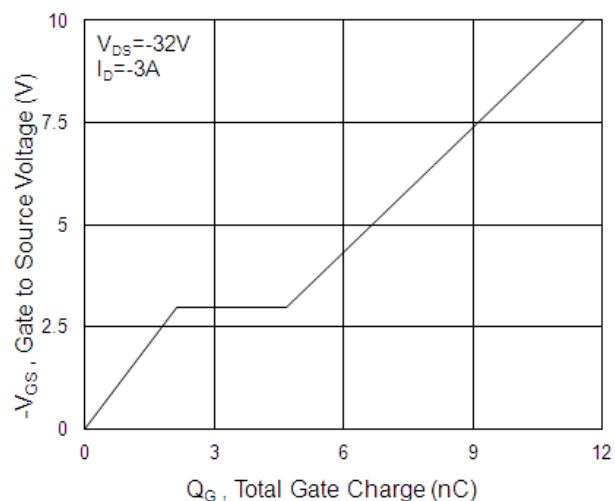
**Fig.1 Typical Output Characteristics**



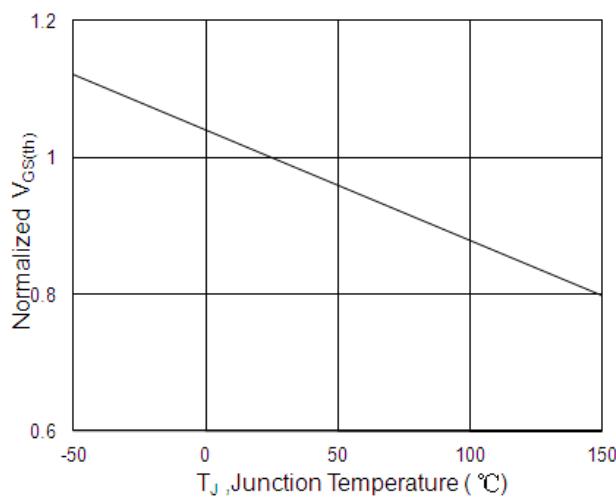
**Fig.2 On-Resistance vs. G-S Voltage**



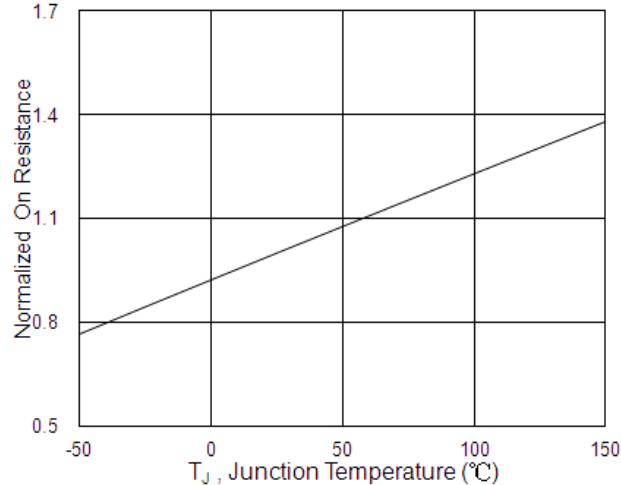
**Fig.3 Forward Characteristics Of Reverse**



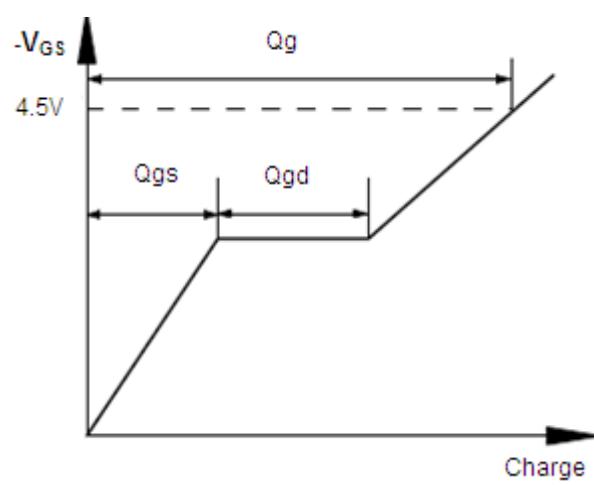
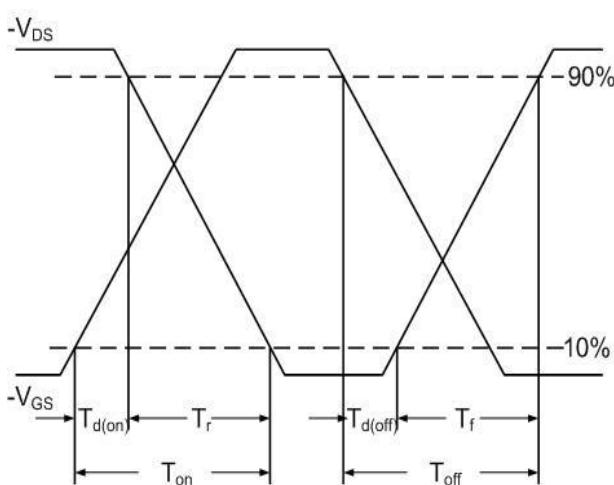
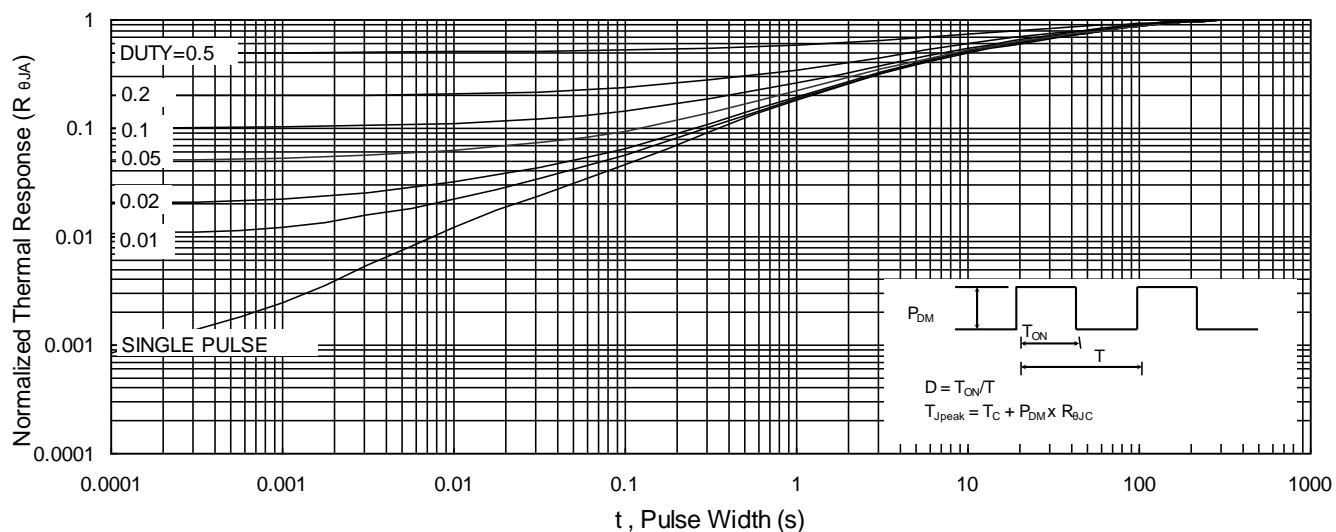
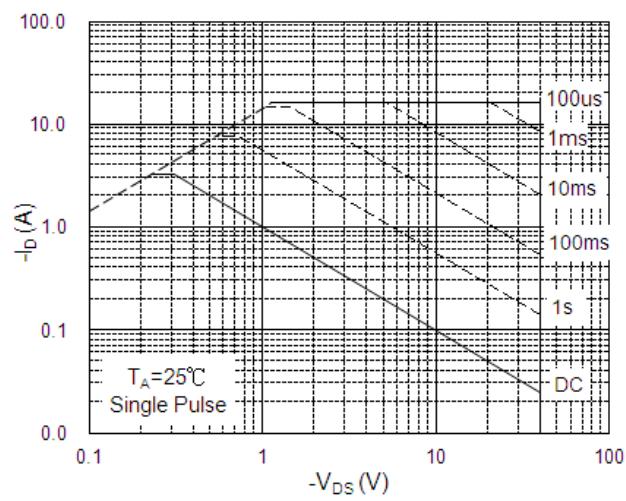
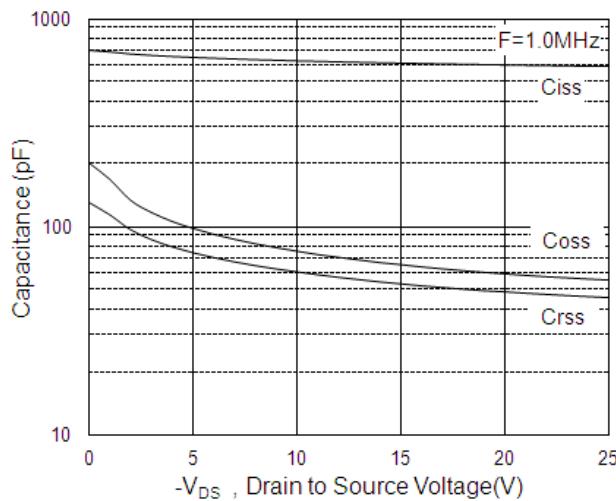
**Fig.4 Gate-Charge Characteristics**



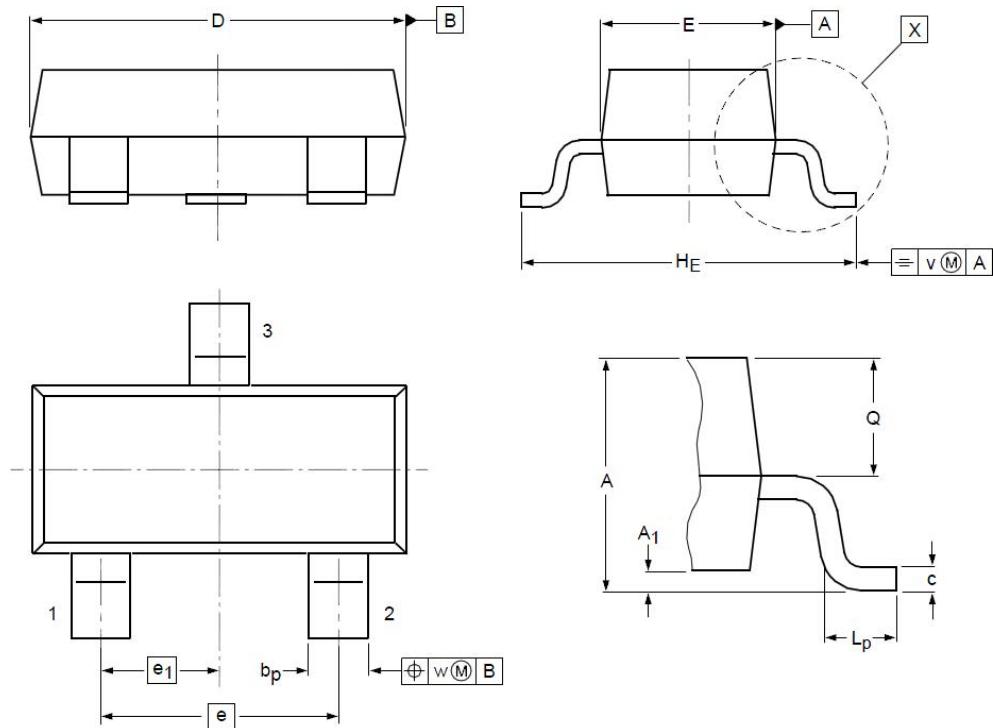
**Fig.5 Normalized  $V_{GS(th)}$  vs.  $T_J$**



**Fig.6 Normalized  $R_{DS(on)}$  vs.  $T_J$**



### SOT23-3L Package Outline Dimensions



<b>Symbol</b>	<b>Dimensions (unit:mm)</b>			<b>Symbol</b>	<b>Dimensions (unit:mm)</b>		
	<b>Min</b>	<b>Typ</b>	<b>Max</b>		<b>Min</b>	<b>Typ</b>	<b>Max</b>
<b>A</b>	0.90	1.07	1.25	<b>e<sub>1</sub></b>	--	0.95	--
<b>A<sub>1</sub></b>	0.01	0.05	0.10	<b>H<sub>E</sub></b>	2.50	2.80	3.00
<b>b<sub>p</sub></b>	0.30	0.40	0.50	<b>L<sub>P</sub></b>	0.30	0.45	0.60
<b>c</b>	0.10	0.15	0.20	<b>Q</b>	0.23	0.28	0.33
<b>D</b>	2.70	2.90	3.10	<b>V</b>	--	0.20	--
<b>E</b>	1.40	1.55	1.75	<b>W</b>	--	0.20	--
<b>e</b>	--	1.90	--				